1

	Application No.	Applicant(s)
Notice of Allowability	10/616,594	GHYSELEN ET AL.
	Examiner	Art Unit
	Mark A Osele	1734
The MAILING DATE of this communication appe All claims being allowable, PROSECUTION ON THE MERITS IS herewith (or previously mailed), a Notice of Allowance (PTOL-85) NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIG of the Office or upon petition by the applicant. See 37 CFR 1.313	(OR REMAINS) CLOSED in this ap or other appropriate communication GHTS. This application is subject t	oplication. If not included
1. This communication is responsive to application filed July 9	<u>), 2003</u> .	
2. ☑ The allowed claim(s) is/are <u>1-23</u> .		
3. $igspace$ The drawings filed on <u>16 October 2003</u> are accepted by the	Examiner.	
 4. Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b)		
Attachment(s) I. ☑ Notice of References Cited (PTO-892) Z. ☐ Notice of Draftperson's Patent Drawing Review (PTO-948) B. ☑ Information Disclosure Statements (PTO-1449 or PTO/SB/08) Paper No./Mail Date 07092003 C. ☐ Examiner's Comment Regarding Requirement for Deposit of Biological Material	6. ☐ Interview Summary Paper No./Mail Date), 7. ☐ Examiner's Amendm	te

Art Unit: 1734

REASONS FOR ALLOWANCE

The following is an examiner's statement of reasons for allowance: None of the prior art, either alone or in combination suggest applicants' invention. The Japanese Patent Publication 10093122 (submitted by applicant) shows a method of fabricating substrates by forming a flat face on a raw ingot, implanting atomic species to a controlled depth to create a zone of weakness, bonding a support to the front face of the ingot, and detaching from the ingot at the zone of weakness that portion of the top layer that is bonded to the support to form the substrate, but fails to show the support to have a smaller surface area than the ingot. None of the additionally cited references show or suggest modifying Japanese Patent Publication 10093122 by making the support have a smaller surface area than the ingot.

Yamaguchi also shows separating an ingot into wafers by ion implantation at a desired depth and striking with a knife edge but fails to suggest the use of a support member with a smaller surface area than the ingot.

Hillberry et al. shows separating an ingot into wafers by fracturing the ingot along a line of weakness.

Bruel '043, Aspar et al., Zhou et al., Srikrishnan, Mitani et al., Henley et al., and Kang et al. each show various steps in transferring a portion of a substrate to a support member bonded thereto along a line of weakness formed by ion implantation.

Application/Control Number: 10/616,594

Art Unit: 1734

Page 3

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Mark A Osele whose telephone number is 571-272-1235. The examiner can normally be reached on M-F 9:30-6:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Christopher Fiorilla can be reached on 571-272-1187. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

MARK A. ÖSELE PRIMARY EXAMINER

November 1, 2004